

# Smart High-Side Power Switch Two Channels: 2 x $25m\Omega$ IntelliSense

#### **Product Summary**

Operating voltage	V <sub>bb(on)</sub>	4,5	V	
		( Loaddur		
Active	channels	one	two parallel	
On-state resistance	R <sub>ON</sub>	25	13	mΩ
Nominal load current	I <sub>L(nom)</sub>	5.9	8,4	A
Current limitation Low	I <sub>L(SCr)</sub>		A	
High				

#### Package



#### **General Description**

- N channel vertical power MOSFET with charge pump, ground referenced CMOS compatible input and diagnostic feedback, monolithically integrated in Smart SIPMOS<sup>®</sup> technology.
- Providing embedded protective functions.
- Extern adjustable current limitation.

#### Application

- All types of resistive, inductive and capacitive loads
- $\bullet\,\mu C$  compatible high-side power switch with diagnostic feedback for 12 V grounded loads
- Due to the adjustable current limitation best suitable for loads with high inrush currents, so as lamps
- Replaces electromechanical relays, fuses and discrete circuits

#### **Basic Functions**

- Very low standby current
- CMOS compatible input
- Improved electromagnetic compatibility (EMC)
- Stable behaviour at low battery voltage

#### **Protection Functions**

- Reverse battery protection with external resistor
- Short circuit protection
- Overload protection
- Current limitation
- Thermal Shutdown
- Overvoltage protection with external resistor
- Loss of GND and loss of V<sub>bb</sub> protection
- Electrostatic discharge Protection (ESD)

#### **Diagnostic Function: IntelliSense**

- Proportional load current sense ( with defined fault signal during thermal shutdown and overload )
- Additional open load detection in OFF state
- Suppressed thermal toggling of fault signal









# **Functional diagram**





# Pin definition and function

Pin	Symbol	Function
4	IN1	Input 1,2 activates channel1,2 in case of logic high signal
7	IN2	
5	IS1	Diagnostic feedback 1 & 2 of channel 1,2
		On state: advanced current sense with defined signal in case
6	IS2	of overload or short circuit
		Off state: High on failure
3	GND 1/2	Ground of chip
1,10,	V <sub>bb</sub>	Positive power supply voltage. Design the wiring for the
11,15,		simultaneous max. short circuit currents from channel 1 to 2 and
16,20		also for low thermal resistance
8	CLA	Current limit adjust, the current limit for both channels can be
		chosen as high ( potential < 2V ) or low ( potential > 4V ).
17,18,19	OUT1	Output 1,2 protected high-side power output of channel 1,2.
12,13,14	OUT2	Design the wiring for the max. short circuit current.
2,9	N.C.	Not connected

# Pin configuration

(top vie	ew)		
V <sub>bb</sub>	1•	20	V <sub>bb</sub>
N.C.	2	19	OUT1
GND 1/2	3	18	OUT1
IN1	4	17	OUT1
IS1	5	16	V <sub>bb</sub>
IS2	6	15	V <sub>bb</sub>
IN2	7	14	OUT2
CLA 1/2	8	13	OUT2
N.C.	9	12	OUT2
V <sub>bb</sub>	10	11	V <sub>bb</sub>



#### **Maximum Ratings** at $T_i$ =25°C, unless otherwise specified

Parameter	Symbol	Value	Unit
Supply voltage (overvoltage protection see page 6)	V <sub>bb</sub>	28 <sup>1)</sup>	V
Supply voltage for full short circuit protection; $T_i = -40150^{\circ}C$	V <sub>bb(SC)</sub>	28 <sup>2)</sup>	
Maximum voltage across DMOS	V <sub>ON</sub>	52	
Load dump protection <sup>3)</sup> $V_{\text{LoadDump}} = V_{\text{A}} + V_{\text{S}}$ ; $V_{\text{A}} = 13,5 \text{ V}$	V <sub>Loaddump</sub>		
In = low or high; $t_{d}$ = 400 ms; $R_{l}^{(4)}$ = 2 $\Omega$			
R <sub>L</sub> = 2.25 Ω		40	
$R_{\rm L}$ = 6.8 $\Omega$		53	
Load current (Short - circuit current, see page 7)	IL	$I_{L(lim)}^{5)}$	A
Operating temperature range	Tj	-40+150	°C
Storage temperature range	T <sub>stg</sub>	-55+150	
Dynamical temperature rise at switching	dT	60	К
Power dissipation <sup>6)</sup> (DC), one channel active $T_A = 85 \text{ °C}$	P <sub>tot</sub>	1,4	W
Maximal switchable inductance, single pulse	Z <sub>L(s)</sub>		mH
$V_{bb}$ =12V, $T_{jstart}$ =150°C; (see diagrams on page 12)			
$I_{\rm L}$ = 6 A, $E_{\rm AS}$ = 0.319 J, $R_{\rm L}$ = 0 $\Omega$ , one channel:		9.8	
$I_{\rm L}$ = 12 A, $E_{\rm AS}$ = 0.679 J, $R_{\rm L}$ = 0 $\Omega$ , two parallel channels:		5.2	
Electrostatic discharge voltage IN:	V <sub>ESD</sub>	1.0	kV
(Human Body Model) IS:		2.0	
according to ANSI EOS/ESD - S5.1 - 1993 , ESD STM5.1 - 1998 OUT:		4.0	
Continuous input voltage	V <sub>IN</sub>	-1016	V
Voltage at current limit adjustment pin	V <sub>CLA</sub>	-1016	
Current limit adjustment current	I <sub>CLA</sub>	±5.0	mA
Current through input pin (DC)	/ <sub>IN</sub>	±5.0	
Current through sense (DC) (see page 11)	I <sub>IS</sub>	-510	

<sup>1</sup>18...28 V for 100 hours

<sup>2</sup>only single pulse,  $R_L = 200 \text{ m}\Omega$ ;  $L = 8 \mu\text{H}$ ; R and L are describing the complete circuit impedance including line, contact and generator impedances.

<sup>3</sup>Supply voltage higher than  $V_{bb(AZ)}$  require an external current limit for the GND (150 $\Omega$  resistor) and sense pin.

 ${}^{4}R_{I}$  = internal resistance of the load dump test pulse generator.

<sup>5</sup>Current limit is a protection function. Operation in current limitation is considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

<sup>6</sup>Device on 50mm\*50mm\*1.5mm epoxy PCB FR4 with 6 cm2 (one layer, 70 $\mu$ m thick) copper area for V<sub>bb</sub> connection. PCB is vertical without blown air.



Electrical Characteristics						
Parameter and Conditions, each of the two channels		Symbol	Values			Unit
at T <sub>j</sub> = -40+150 °C, V <sub>bb</sub> = 916 °	V, unless otherwise specified		min.	typ.	max.	
Thermal Resistance				-	-	
junction - soldering point	each channel:	R <sub>thJS</sub>	-	18	-	K/W
junction - ambient <sup>1)</sup>	one channel active:	<i>R</i> thJA	-	44	-	K/W
	all channels active:			42		
Load Switching Capabilitie	es and Characteristics					
On-state resistance (V <sub>bb</sub> to 0	OUT), (see page 13)	R <sub>ON</sub>				mΩ
<i>T</i> <sub>j</sub> = 25 °C, <i>I</i> <sub>L</sub> = 5 A,	each channel:		-	21	25	
<i>T</i> <sub>j</sub> = 150 °C,	each channel:		-	42	50	
<i>T</i> <sub>j</sub> = 25 °C,	two parallel channels:		-	11	13	
Nominal load current <sup>1)</sup>		I <sub>L(nom)</sub>				A
<i>T</i> <sub>a</sub> = 85°C, <i>T</i> <sub>j</sub> ≤ 150°C ,	one channel active:		5.4	5.9	-	
two channe	ls active, per channel:		3.9	4.2	-	
Output voltage drop limitatio	n at small load currents	V <sub>ON(NL)</sub>	-	40	-	mV
<i>I</i> <sub>L</sub> = 0.5 A						
Output current while GND di	sconnected <sup>2)</sup>	I <sub>L(GNDhigh)</sub>	-	-	2	mA
( see diagram page 12 )						
$V_{\rm IN} = 0 V$						

<sup>1</sup>Device on 50mm\*50mm\*1.5mm epoxy PCB FR4 with 6 cm2 (one layer, 70 $\mu$ m thick) copper area for V<sub>bb</sub> connection. PCB is vertical without blown air.

<sup>2</sup>not subject to production test, specified by design



#### **Electrical Characteristics**

Parameter and Conditions, each of the two channels	Symbol	Values			Unit
at $T_{i}$ = -40+150 °C, $V_{bb}$ = 916 V, unless otherwise specified		min.	typ.	max.	
Load Switching Capabilities and Characteristics				-	- 
Turn-on time <sup>1)</sup> to 90% $V_{OUT}$	t <sub>on</sub>	-	90	200	μs
$R_{\rm L}$ = 12 Ω, $V_{\rm bb}$ = 12 V					
Turn-off time <sup>1</sup> ) to 10% $V_{OUT}$	t <sub>off</sub>	-	100	220	
$R_{\rm L}$ = 12 Ω, $V_{\rm bb}$ = 12 V					
Slew rate on <sup>1)</sup> 10 to 30% V <sub>OUT</sub> ,	dV/dt <sub>on</sub>	0.1	0.25	0.45	V/µs
$R_{\rm L}$ = 12 Ω, $V_{\rm bb}$ = 12 V					
Slew rate off <sup>1)</sup> 70 to 40% V <sub>OUT</sub> ,	-dV/dt <sub>off</sub>	0.09	0.25	0.4	
$R_{\rm L}$ = 12 Ω, $V_{\rm bb}$ = 12 V					
Slew rate on <sup>1</sup> ) 10 to 30% V <sub>OUT</sub> , $R_{L} = 12 \Omega, V_{bb} = 12 V$ Slew rate off <sup>1</sup> ) 70 to 40% V <sub>OUT</sub> , $R_{L} = 12 \Omega, V_{bb} = 12 V$	dV/dt <sub>on</sub> -dV/dt <sub>off</sub>	0.1	0.25	0.45	V/µs

#### **Operating Parameters**

Operating voltage <sup>2)</sup>	V <sub>bb(on)</sub>	4.5	-	28	V
Overvoltage protection <sup>3)</sup>	V <sub>bb(AZ)</sub>	41	47	52	
<i>I</i> <sub>bb</sub> = 40 mA					
Standby current <sup>4)</sup>	I <sub>bb(off)</sub>				μA
(see diagram on page 13)					
<i>T</i> <sub>j</sub> = −40+25 °C, <i>V</i> <sub>IN</sub> = 0 V		-	5	7.5	
<i>T</i> <sub>j</sub> = 150 °C		-	-	20	

<sup>1</sup>See timing diagram on page 14.

 $2_{18V\ldots 28V}$  for 100 hours

<sup>3</sup>Supply voltages higher than  $V_{bb(AZ)}$  require an external current limit for the status pin and GND pin (e.g. 15 $\Omega$ ). See also  $V_{Out(CL)}$  in table of protection functions and circuit diagram on page 11.

<sup>4</sup>Measured with load; for the whole device; all channels off.



Electrical Characteristics							
Parameter and Condition	<b>is,</b> each of th	e two channels	Symbol		Values		Unit
at <i>T</i> <sub>j</sub> = -40+150 °C, <i>V</i> <sub>bb</sub> = 91	6 V, unless c	otherwise specified		min.	typ.	max.	
<b>Operating Parameters</b>					-		
Off-State output current (included in <i>I</i> <sub>bb(off)</sub> )		I <sub>L(off)</sub>	-	1.5	8	μA	
$V_{\rm IN}$ = 0 V, each channel							
Operating current <sup>1)</sup>			I <sub>GND</sub>	-	1.6	4	mA
$V_{\rm IN}$ = 5 V, per active chan	nel						
Protection Functions <sup>2)</sup>							
Current limit, ( see timing diagrams, page 15 )		I <sub>L(LIM)</sub>				A	
Low level; if potential at CLA = high			7	11	14		
High level; if potential at CLA = low			40	50	60		
Current limit adjustment threshold voltage		V <sub>CLA(T-)</sub>	2.0	-	-	V	
			V <sub>CLA(T+)</sub>	-	-	4.0	
Repetitive short circuit cur	rent limit		I <sub>L(SCr)</sub>				A
$T_j = T_{jt}$ (see timing diagrams	on page 15)	1					
High level	one a	active channel:		-	40	-	
	two act	ve channels <sup>3)</sup> :		-	40	-	
Low level	one a	active channel:		-	7	-	
	two act	ve channels <sup>3)</sup> :		-	7	-	
Initial short circuit shutdow	n time	low level:	t <sub>off(SC)</sub>	-	3.5	-	ms
$T_{i,start} = 25^{\circ}C$ ; $V_{bb} = 13,5 V$ high level:			-	0.75	-		
Output clamp (inductive load switch off) <sup>4)</sup>		V <sub>OUT(CL)</sub>	-	-15	-	V	
<i>I</i> <sub>L</sub> = 40 mA							
Thermal overload trip temp	perature		T <sub>it</sub>	150	170	-	°C
Thermal hysteresis			$\Delta T_{\rm it}$	-	10	-	K

<sup>1</sup>Add  $I_{IS}$ , if  $I_{IS} > 0$ 

<sup>2</sup>Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

<sup>3</sup>At the beginning of the short circuit the double current is possible for a short time.

<sup>4</sup>If channels are connected in parallel, output clamp is usually accomplished by the channel with the lowest  $V_{OUT(CL)}$ .



Electrical Characteristics						
Parameter and Conditions, each of the two channels	Symbol	Values			Unit	
at $T_{j}$ = -40+150 °C, $V_{bb}$ = 916 V, unless otherwise specified		min.	typ.	max.		
Diagnostic Characteristics						
Open load detection voltage	V <sub>OUT(OL)</sub>	2	3.2	4.4	V	
Internal output pull down <sup>1)</sup>	R <sub>OUT(PD)</sub>	11	23	35	kΩ	
V <sub>OUT</sub> = 13.5 V						
Current sense ratio, static on-condition	k <sub>ILIS</sub>					
$k_{\rm ILIS} = I_{\rm L} : I_{\rm IS}$						
<i>I</i> <sub>L</sub> = 0.5 A		4640	5800	6960		
<i>I</i> <sub>L</sub> = 3 A		4900	5400	5900		
$I_{\rm L} = 6  {\rm A}$		4900	5350	5800		
Sense signal in case of fault-conditions <sup>2)</sup>	V <sub>fault</sub>	5	6.2	7.5	V	
in off-state						
Current saturation of sense fault signal	/ <sub>fault</sub>	4	-	-	mA	
Sense signal delay after thermal shutdown <sup>3)</sup>	t <sub>delay(fault)</sub>	-	-	1.2	ms	
Current sense output voltage limitation	V <sub>IS(lim)</sub>	5.4	6.5	7.3	V	
$I_{\rm IS} = 0$ , $I_{\rm L} = 5$ A						
Current sense leakage/offset current	I <sub>IS(LH)</sub>	-	-	5	μA	
$V_{\rm IN} = 5 \text{ V}, \ I_{\rm L} = 0 \ , \ V_{\rm IS} = 0$						
Current sense settling time to $I_{IS}$ static ±10%	t <sub>son(IS)</sub>	-	-	400	μs	
after positive input slope <sup>4)</sup> , $I_{L} = 0$ to 5A						
Current sense settling time to $I_{IS}$ static ±10%	t <sub>slc(IS)</sub>	-	-	300		
after change of load current <sup>4</sup> ), $I_{\rm I}$ = 2.5 to 5A						

**Electrical Characteristics** 

<sup>1</sup>In case of floating output, the status doesn't show open load.

<sup>2</sup>Fault condition means output voltage exceeds open load detection voltage  $V_{OUT(OL)}$ 

<sup>3</sup>In the case of thermal shutdown the  $V_{\text{fault}}$  signal remains for  $t_{\text{delay}(\text{fault})}$  longer

than the restart of the switch ( see diagram on page 16 ). Not subject to production test, specified by design.

<sup>4</sup>not subject to production test, specified by design



#### **Electrical Characteristics**

Parameter	Symbol	Values			Unit
at $T_j$ = -40+150 °C, $V_{bb}$ = 916 V, unless otherwise specified		min.	typ.	max.	
Diagnostic Characteristics					
Status invalid after negative input slope	<i>t</i> d(SToff)	-	-	1.2	ms
Status invalid after positive input slope	t <sub>d(STOL)</sub>	-	-	20	μs
with open load					
Input Feedback <sup>1)</sup>				-	
Input resistance (see circuit page 11)	R <sub>I</sub>	2.0	3.5	5.5	kΩ
Input turn-on threshold voltage	V <sub>IN(T+)</sub>	I	I	2.4	V
Input turn-off threshold voltage	V <sub>IN(T-)</sub>	1.0	-	-	
Input threshold hysteresis	$\Delta V_{\rm IN(T)}$	-	0.5	-	
Off state input current	I <sub>IN(off)</sub>	3	-	40	μA
$V_{\rm IN} = 0.4 \ V$					
On state input current	I <sub>IN(on)</sub>	20	50	90	
$V_{\rm IN} = 5 V$					

#### **Reverse Battery**<sup>2)</sup>

Reverse battery	-V <sub>bb</sub>	-	-	27	V
Drain-source diode voltage ( $V_{OUT} > V_{bb}$ )	-V <sub>ON</sub>	-	330	-	mV
<i>T</i> <sub>j</sub> = 150 °C, <i>I</i> <sub>bb</sub> = -10 mA					

<sup>1</sup>If ground resistors  $R_{GND}$  are used, add the voltage drop across these resistor.

<sup>2</sup>Requires a 150Ω resistor in GND connection. The reverse load current through the intrinsic drain-source diode has to be limited by the connected load. Power dissipation is higher compared to normal operating conditions due to the voltage drop across the drain-source diode. The temperature protection is not active during reverse current operation! Input and status currents have to be limited. (see max. ratings page 4)



#### Truth Table - for each of the two channels

	Input	Output	Diagnostic
	level	level	output
Normal	L	L	<u>Z</u> 1)
Operation	Н	V <sub>bb</sub>	I <sub>IS</sub> = I <sub>L</sub> / kilis
Current			
Limitation <sup>2)</sup>	н	v <sub>bb</sub>	V <sub>fault</sub>
Short circuit	L	L	Z <sup>1)</sup>
to GND	Н	L	V <sub>fault</sub>
Overtemperature	L	L	Z <sup>1)</sup>
	Н	L	V <sub>fault</sub>
Short circuit	L	V <sub>bb</sub>	V <sub>fault</sub>
to V <sub>bb</sub>	Н	V <sub>bb</sub>	$< I_{\rm IS} = I_{\rm L} / \rm kilis^{3}$
Open load	L	>V <sub>out(OL)</sub>	V <sub>fault</sub>
	Н	V <sub>bb</sub>	Z <sup>1)</sup>

L = "Low" Level Z = high impedance, potential depends on external circuit

H = "High" Level  $V_{fault}$  = 5V typ., constant voltage independent of external sense resistor.

Parallel switching of channels is possible by connecting the inputs and outputs parallel. The current sense ouputs have to be connected with a single sense resistor.

#### Terms



Leadframe (V<sub>bb</sub>) is connected to pin 1,10,11,15,16,20

<sup>1</sup>L-potential by using a sense resistor

<sup>2</sup>Current limitation is only possible while the device is switched on.

<sup>3</sup>Low ohmic short to  $V_{bb}$  may reduce the output current  $I_L$  and therefore also the sense current  $I_{IS}$ .



#### Input circuit ( ESD protection ), IN1 or IN2



The use of ESD zener diodes as voltage clamp at DC conditions is not recommended.

#### Sense-Status output, IS1 or IS2

ON-State: Normal operation:  $I_{S} = I_{L} / _{kILIS}$ 



ESD zener diode:  $V_{ESD}$  = 6,1 V typ., max. 14 mA ; ON-State: Fault condition so as thermal shut down or current limitation



 $V_{\text{fault}} = 6 \text{ V typ}$ ;  $V_{\text{fault}} < V_{\text{ESD}}$  under all conditions OFF-State diagnostic condition: Open Load, if  $V_{\text{OUT}} > 3 \text{ V typ.}$ ; IN low



ESD-Zener diode: 6,1V typ., max. 5mA;  $R_{ST(ON)} < 375\Omega$  at 1,6mA.. The use of ESD zener diodes as voltage clamp at DC conditions is not recommended.

#### Inductive and overvoltage output clamp, OUT1 or OUT2



 $V_{OUT}$  clamped to  $V_{OUT(CL)}$  = -15 V typ.

#### **Overvolt. Protection of logic part** OUT1 or OUT2



$$\begin{split} V_{Z1} &= 6,1 \text{V typ.}, \, V_{Z2} = 47 \text{V typ.}, \, R_{\text{GND}} = 150 \Omega \ , \\ R_{\text{IS}} &= 1 \text{k} \Omega \ , \, R_{\text{I}} = 3,5 \text{k} \Omega \ \text{typ.} \end{split}$$



#### Reverse battery protection OUT1 or OUT2



 $V_{Z1} = 6,1V \text{ typ.}, V_{Z2} = 47V \text{ typ.}, R_{GND} = 150\Omega$  $R_{\text{IS}} = 1k\Omega, R_{\text{I}} = 3,5k\Omega \text{ typ.}$ 

In case of reverse battery the load current has to be limited by the load. Protection functions are not active.

#### Open load detection, OUT1 or 2

Off-state diagnostic condition: Open load, if  $V_{OUT}$  > 3 V typ.; IN = low



# **GND** disconnect



Any kind of load.

Vbb disconnect with energized inductive load



For inductive load currents up to the limits defined by  $Z_{L}$  each switch is protected against loss of  $V_{bb}$ .

(max. ratings and diagram on page 12) Consider at your PCB layout that in the case of Vbb disconnection with energized inductive load all the load current flows through the GND connection.

# Inductive load switch-off energy dissipation



Energy stored in load inductance:  $E_L = \frac{1}{2} * L * I_L^2$ While demagnetizing load inductance, the enérgy dissipated in PROFET is  $E_{AS} = E_{bb} + E_L - E_R = V_{ON(CL)} * i_L(t) dt$ , with an approximate solution for  $R_L > 0\Omega$ :

$$E_{AS} = \frac{I_L * L}{2 * R_L} * (V_{bb} + |V_{OUT(CL)|}) * \ln(1 + \frac{I_L * R_L}{|V_{OUT(CL)|}})$$



# Maximum allowable load inductance for a single switch off (one channel) L =f(IL); $T_{jstart}$ = 150°C, $V_{bb}$ = 12V, $R_L$ = 0 $\Omega$



# Typ. on-state resistance $R_{ON} = f(V_{bb}, T_j); I_L = 5 A; V_{in} = high$



#### Typ. standby current

*I*<sub>bb(off)</sub> = f(*T*<sub>j</sub>) ; *V*<sub>bb</sub> = 16 V ; *V*<sub>IN1,2</sub> = low





# **Timing diagrams**

All channels are symmetric and consequently the diagrams are valid for channel 1 and channel 2.

**Figure 1a:** Switching a resistive load, change of load current in on-condition



The sense signal is not valid during settling time after turn on or change of load current.  $tslc(IS) = 300 \ \mu s \ max$ .





proper turn on under all conditions

**Figure 1c:** Behaviour of sense output: Sense current ( $I_S$ ) and sense voltage ( $V_S$ ) as function of load current dependent on the sense resistor. Shown is  $V_S$  and  $I_S$  for three different sense resistors. Curve 1 refers to a low resistor, curve 2 to a medium-sized resistor and curve 3 to a big resistor. Note, that the sense resistor may not falls short of a minimum value of 500 $\Omega$ .



 $I_{\rm S} = I_{\rm L} / k_{\rm ILIS}$  $V_{\rm IS} = I_{\rm S} * R_{\rm IS}; R_{\rm IS} = 1 {\rm k} \Omega$  nominal  $R_{\rm IS} > 500 \Omega$ 



Figure 2a: Switching a lamp



**Figure 2b:** Switching a lamp with current limit: The behaviour of  $I_S$  and  $V_S$  is shown for a resistor, which refers to curve 1 in figure 1c



**Figure 3a:** Short circuit: Shut down by overtemperature, reset by cooling



Heating up may require several milliseconds, depending on external conditions.  $I_{L(lim)} = 50A$  typ. increases with decreasing temperature.

**Figure 3b:** Turn on into short circuit, shut down by overtemperature, restart by cooling ( channel 1 and 2 switched parallel )





# Figure 4a: Overtemperature

Reset if  $T_j < T_{jt}$ The behaviour of  $I_S$  and  $V_S$  is shown for a resistor, which refers to curve 1 in figure 1c.





Figure 5a:Open-load: detection in OFF-state, turn on/off to open load.

Open load of channel 1; other channels normal opertaion.



 $t_{\text{off}}$  = 220µs max.;  $t_{\text{d(SToff)}}$  = 1,2ms max. with pull up resistor at output

<sup>1</sup>This range for the current sense ratio refers to all devices. The accuracy of the  $k_{\text{ILIS}}$  can be raised by calibrating the value of  $k_{\text{ILIS}}$  for every single device.



# Package and ordering code

all dimensions in mm

#### P-DSO-20-21



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